THE 9TH INTERNATIONAL CONFERENCE ON RESIDUAL STRESS

October 7-9, 2012 Congress-Centre, Garmisch-Partenkirchen, Germany

THE 9TH INTERNATIONAL CONFERENCE on

Residual Stresses is intended as a continuation of the successful series initiated in Garmisch-Partenkirchen (Germany, 1986) and continued in Nancy (France, 1988), Tokushima (Japan, 1991), Baltimore (USA, 1994), Linkoping (Sweden, 1997), Oxford (UK, 2000), Xi'an (China, 2004) and Denver (USA, 2008).

The conference provides a forum for scientists, students, and engineers interested in the prediction, evaluation, control, and application of residual stresses. The aim of this conference is to give equal emphasis to the measurement, modelling, and utilization of residual stress/strain data. Both the scientific and engineering aspects of these topics, such as the influence of residual stress fields on distortion, damage initiation, propagation, component lifetimes, and failure, will be addressed. Emphasis will be laid on method development and current hot topics of great interest, as, for example, stresses in nanosized systems, stress analysis using synchrotron radiation, etc.

CONFERENCE LOCATION

The conference will be held October 7-9 2012 in the Congress Centre in Garmisch-Partenkirchen (Germany). Garmisch-Partenkirchen is located in the Bavarian Alps at the foot of the mountain 'Zugspitze', the highest mountain in Germany (2,962 m/9,724 ft).

Garmisch-Partenkirchen can be reached by car or by train. From Munich Hauptbahnhof, the train ride takes about 1½ hours. Munich International Airport provides connections to many destinations in Europe and abroad.

Accommodation in Garmisch-Partenkirchen can be booked in many different guest houses and hotels. A wide range of accommodation standards and prices, ranging from bed & breakfast-type accommodation to five-star hotels is available. Further information can be found soon on the web pages (keep an eye on www.mf.mpg.de/icrs9).

CALL FOR CONTRIBUTIONS

Participants are invited to submit an abstract of their contribution using the format described in the Instruction for Authors section of the website. The abstracts will be collected in a booklet available at the conference. Contributions can be presented as posters or oral communications, on the basis of author's request and evaluation by the scientific committee. It is planned to publish papers of all accepted contributions in the form of Conference Proceedings. Manuscripts should be submitted at the Conference.

SUPPORT

A number of grants for colleagues from less-favoured countries will be made available. To be eligible, candidates should provide a brief curriculum vitae and the abstract of their intended contribution. Support can be partial or total, depending on fund availability.

DEADLINES AND IMPORTANT DATES

Abstract submission: 29th February 2012 Acceptance notification: 31st March 2012 Registration deadline (*early registration fee*): 15th April 2012 Registration deadline (*full fee*): 1st July 2012

FEES

The conference fee including lunches and dinners as given in the schedule below as well as coffee breaks, abstract booklet and conference proceedings will be in the order of $550 \in$ (early registration) for regular participants and about $300 \in$ (early registration) for students. After the deadline for early registration, the fees will increase by about $100 \in$ with respect to



The Congress Centre in Garmisch-Partenkirchen, Germany Photo used with permission: Markt Garmisch-Partenkirchen

the early registration fee. The exact fees depend upon sponsoring and fund availability and will be announced on the web pages as soon as possible (keep an eye on www.mf.mpg. de/icrs9). Please note that all conference fees do not include 7% VAT. The ICRS9 Conference is sponsored by the Max Planck Institute for Metals Research.

PRELIMINARY REGISTRATION

Prospective participants are requested to express their interest in participation by sending an email to icrs9@ mf.mpg.de containing the following in-formation: Name, affiliation and field of interest (e.g. residual stresses in coatings, diffraction measurement of stresses etc) at any time. You will then be added to a mailing list and receive further circulars and updates by email.

CONTACT AND FURTHER INFORMATION

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